



17 August 2026

NEWS RELEASE

Outlook for Enhanced Production Capacity of Copper Foil from 2030 and Beyond

- Responding to market expansion and establishing a new plant in Malaysia to expand monthly production capacity to 5,000 tons for VSP™ and 12 million m² for MicroThin™ -

Mitsui Kinzoku Company, Limited (President: Seiji Ikenobu; “Mitsui Kinzoku”) announces that it plans to further expand production capacity for VSP™ copper foil for high-frequency circuit boards and MicroThin™ beyond the production capacity expansion toward 2030 announced in a previous news release dated August 7, 2026. In order to ensure a continued stable supply of these products to customers given the continued rapid growth expected in the AI and semiconductor markets in 2030 and beyond, Mitsui Kinzoku has formulated plans to newly acquire land in the vicinity of its Malaysia Plant (Mitsui Copper Foil (Malaysia) Sdn. Bhd.) and establish a new plant with monthly production capacities of 1,200 tons for VSP™ and 4 million m² for MicroThin™ from 2031 onward. Combined with its existing production capacity, this will raise Mitsui Kinzoku’s total monthly production capacity to 2,600 tons for VSP™ and 12 million m² for MicroThin™.

Mitsui Kinzoku is also exploring plans to build out its monthly production capacity for VSP™ up to 5,000 tons in response to further market growth.

Mitsui Kinzoku’s VSP™ copper foil for high-frequency circuit boards has been used in servers, routers, switches and other high-performance communication infrastructure equipment because it significantly reduces transmission loss in printed circuit boards at high frequency signal bands. Currently, Mitsui Kinzoku is shifting HVLP5-graded products to the mass production phase for applications relating to AI infrastructure, and these products are increasingly used by leading global technology companies. The demand for Mitsui Kinzoku’s VSP™ is rapidly growing, and it is expected that it will increase.

MicroThin™, carrier-supported ultra-thin copper foil, is a product of Mitsui Kinzoku combining a copper foil thickness ranging from 1.5 µm to 5 µm suitable for forming fine circuits, with multiple types of fine-roughening treatment. It is mainly used for IC substrates, optical modules and motherboards for smartphones (HDI printed circuit boards). Mitsui Kinzoku believes that demand will continue to increase in the future, with demand for IC substrates expanding significantly due to their increasing application in data centers and memories, and their use in optical modules and AI servers.

Mitsui Kinzoku will contribute to the realization of a sustainable society by implementing its vision for 2030, “Building new businesses —and the future— with our material intelligence,” based on its purpose, “We promote the well-being of the world through a spirit of exploration and diverse technologies.”

■ MicroThin™ and VSP™ production capacity (for reference)

	FY2025	FY2026	FY2027	FY2028	FY2030	FY2031	FY2032	FY2033
MicroThin™(10,000 m ² / month)	490	490	520	600	800	1,000	1,000	1,200
VSP™ (tons/month)	720	840	1,000	1,200	1,400	2,000	2,600	*2,600

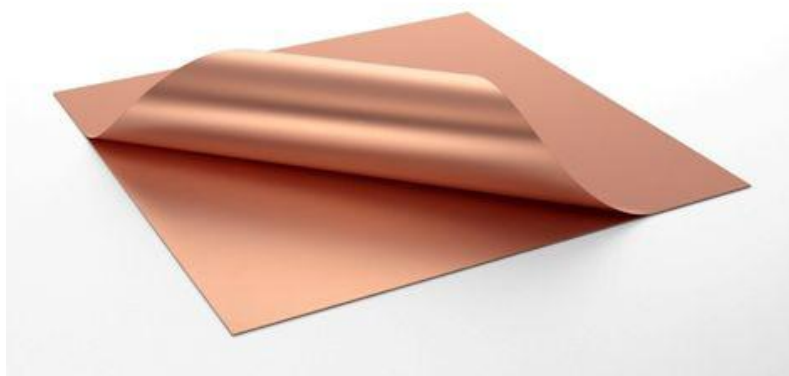
* The land to be acquired will enable monthly production to be expanded to 5,000 tons.

[Contact]

Corporate Communications Department, Corporate Planning & Control Sector, Mitsui Kinzoku Company, Limited

TEL: +81-3-5437-8028 Email: PR@mitsui-kinzoku.com

Picture of MicroThin™



Top: Copper carrier foil (thickness: 18μm or 12μm)

Bottom: Ultra-thin copper foil (thickness: 1.5μm to 5μm)



General-purpose copper foil



VSP™

Picture: A reflection of an apple mango in a copper foil surface

* VSP™ is characterized by its outstanding surface smoothness comparable to that of a mirror.